products and services

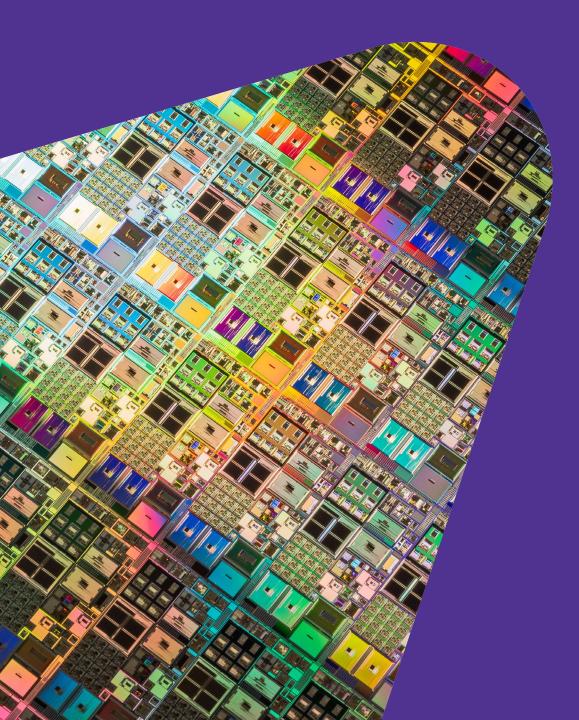
Performance Materials Electronics Specialty Gases Conference

October 2020



The performance materials business of Merck KGaA, Darmstadt, Germany operates as EMD Performance Materials in the U.S. and Canada.



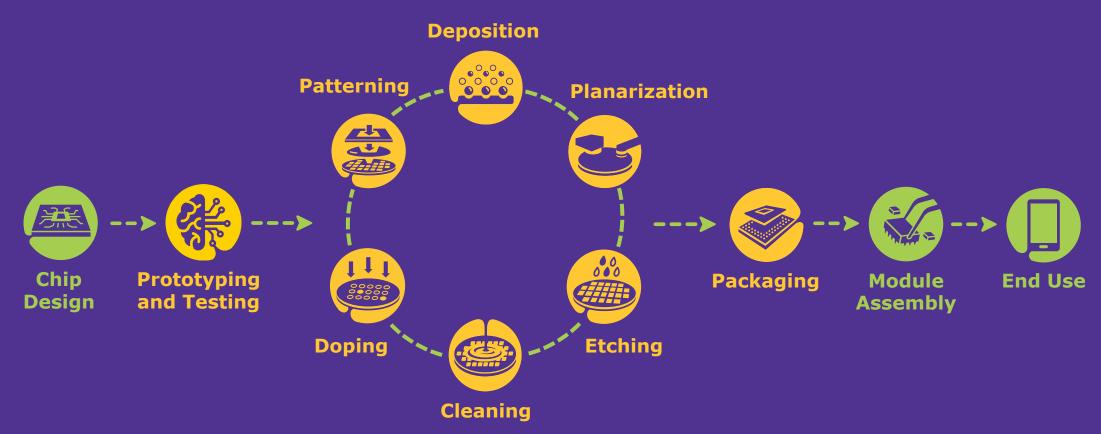


semiconductors at EMD performance materials



the semiconductor industry

Together as one company, we have increased our capabilities in the semiconductor space. We can now **deliver innovation across the value chain.**

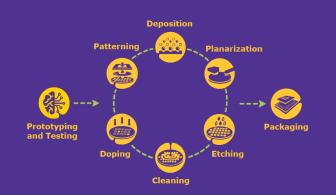




Semiconductor Materials

We deliver innovation across the value chain

The combination of our business creates a **complementary portfolio of materials, equipment and services** for the electronic industry.





Thin Film

Organosilanes & Organometallics for CVD, ALD, PECVD PEALD and FCVD
Spin on dielectrics



Patterning

DSA, Patterning enhancement, Thick film resist **SP&C:** Resist strip, Al PERR,

Advanced IC cleans



Planarization

Slurries: Oxide, Cu Bulk, Cu Barrier, Tungsten Post CMP Cleans



Specialty Gases

Etching Gases: C4F6, CIF3, HCl Deposition Gases: WF6, N2O Dopant Gases: B2H6, AsH3 Cleans Gases: NF3, CIF3



Packaging

Conductive pastes, Thick film resist, Advanced polymer removal



Intermolecular

Advanced materials innovation
High through-put experimentation
High quality material development
services



products & capabilities

Thin Film Solutions





Thin Film solutions



Close collaboration

to enable material innovation and solve unique problems



Application Area

Gap fills
Low-k
3D Structures
Conformal films
Advanced Patterning
Gate stacks/Work Function
Barriers

Contacts
Wordline
Hardmasks

Selective deposition
Displays

R&D

Broad chemistry/materials
science base
Computational Modeling
Chemical synthesis/purification
Applications testing and film
metrology
Containers and delivery

Containers and delivery
Advanced materials analytical
capability

In-fab process characterization Access to Intermolecular capabilities

Key locations



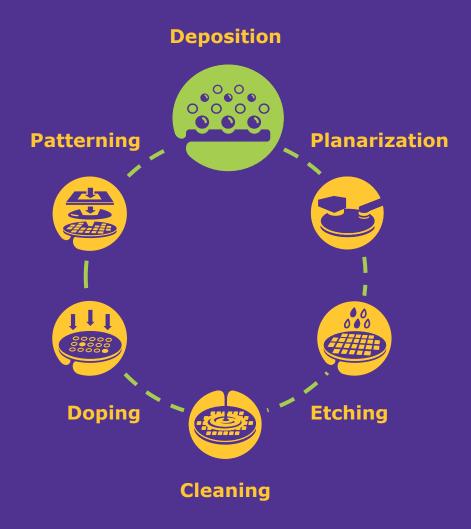


Products

Spin-on
Dielectrics
Organosilanes
Organometallics



Our portfolio



Leading positions in Thin Film solutions:

- Spin-on Dielectrics
- Organosilanes
- Organometallics

Click below to

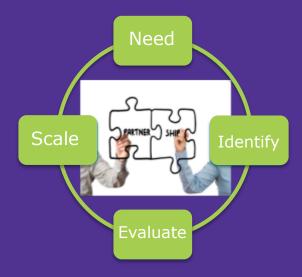
- check out our <u>EMD solutions</u>
- see our legacy <u>Versum offering</u>



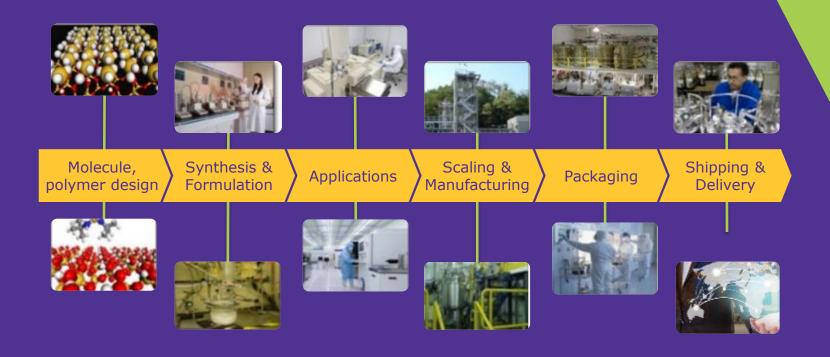
close collaboration

to enable material innovation and solve unique problems

Close collaboration...



...that drives mutually beneficial growth







application areas

- Gap fills: SOD, FCVD, ALD, and CVD
- Low-k: BEOL and FEOL
- **3D Structures:** FinFET, 3D NAND, and Packaging
- Conformal films for high aspect ratio features at both low and high temperatures
- Advanced Patterning
- Gate stacks/Work Function
- Barriers
- Contacts
- Wordline
- Hardmasks
- Selective deposition
- Displays

our offerings

Spin-on Dielectrics

- Existing: Spinfil[®] and Ancillary, RS series,
- New: Spinfil® and RS series next gen, Multi-Color Materials, PSOD

Organosilanes (PECVD, ALD, and FCVD)

- Existing: AP-LTO® and AP-LTN® product lines, PDEMS® franchise for Structure former and Porogen, BTBAS/3DMAS/TEOS/3MS/4MS/TSA
- New products: new ALD precursors; PECVD based advanced Low-k; new FCVD

Organometallics (CVD and ALD)

- Existing: Co/Ta/Al/Ti/Hf/La/Cu
- New: Mo/W/Zr/Ru/Y/Nb
- Differentiation through containers
- Dopants and other specialty chemicals



Technology solutions for:

- Spin-on Dielectric
- Organosilanes
- Organometallics
- Other specialty chemicals

our R&D capabilities

Broad chemistry/thin-film science base

- Silicon based polymers
- Silicon, metal, and dopant precursors
- Organic chemistry

Computational Modeling

- Process modeling
- Molecular modeling

Chemical synthesis/purification

- Bench top, Kilo-scale, and Pilot capabilities
- Full engineering and scale up

Applications testing and film metrology

- Spin-on, PECVD, and ALD deposition: 300mm and screening tools
- State-of-the-art analytical tools

Precursor containers and delivery

Collaboration with the EMD's Delivery System to solve unique problems

Advanced materials analytical capability

In-fab process characterization

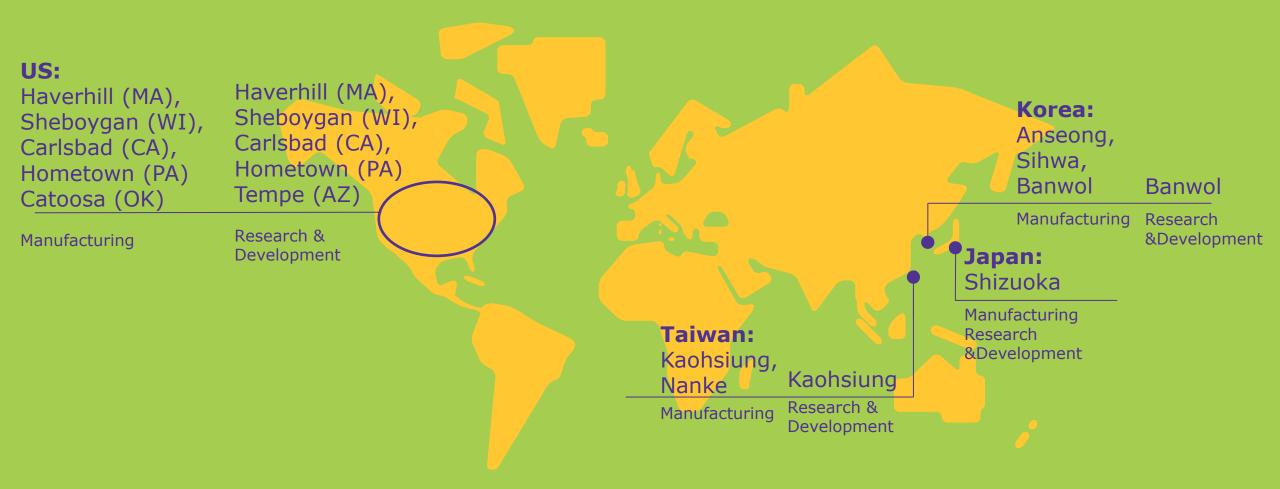
Access to Intermolecular capabilities





Global capabilities & capacities

11 Manufacturing and 8 R&D Facilities





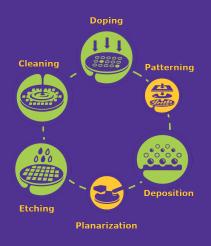
our combined products & capabilities

Specialty Gases





specialty gases



A **recognized leader** in electronics specialty gases and the end-markets we serve



Products

We offer all major Specialty
Gases in the market, covering
following platforms



Etching Gases

Cleaning Gases

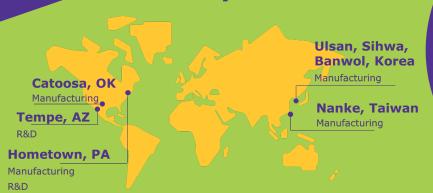
Deposition Gases

Dopant Gases

R&D

New Etching Gases
Product Synthesis
New Hard-Mask Gas

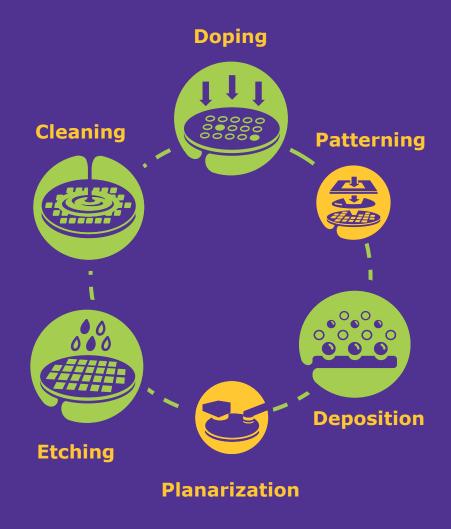
Key locations





specialty cases

Our portfolio



- Leading provider of Specialty
 Gases
- Large Electronics Fluorine franchise
- >40 Broad Specialty Gas product portfolio

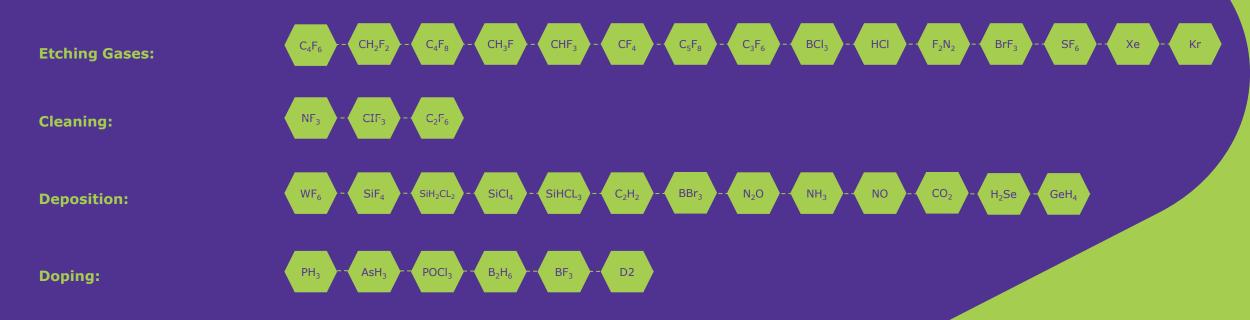
Click below to

- check out our <u>EMD solutions</u>
- see our legacy <u>Versum offering</u>



A **recognized Leader** in electronic specialty gases and the end-markets we serve

Broadest portfolio, geographic reach, technical support, applications know-how and customer intimacy





New Etching Gases

Product Synthesis

New Hard-Mask Gas

new product pevelopment



Focus on **new materials solution development,** partnering with customers



Develop new product matching with customers' technology roadmap



Develop high purity product **synthesis and purification** technology



Global capabilities & capacities





our combined products & capabilities

Planarization





planarization



Global Leader in Chemical Mechanical Planarization (CMP) Technology



Broad product portfolio with strong positions at leading customers

FEOL Dielectrics

 STI, ILD and bulk oxide slurries

MOL MG & Contacts

- W Bulk and Buff slurries
- Co & Mo slurries

BEOL Interconnects

- Cu Bulk slurries
- Cu Barrier slurries



R&D

Innovation in chemical additive and abrasive chemistry

Slurry formation design

Film property characterization and correlation with polishing performance

Integrated slurry and **pCMP** clean design



Key locations

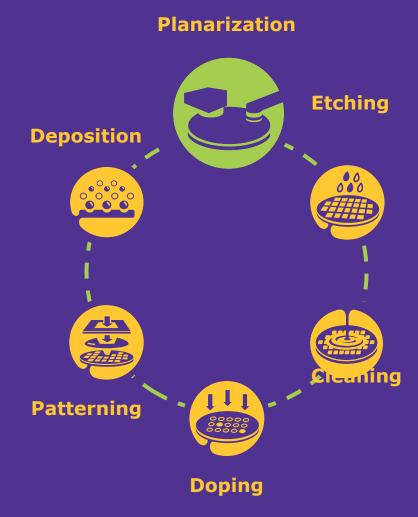


planarization

We have a **broad Chemical Mechanical Planarization (CMP) portfolio**, specifically targeting **innovative new products**

- STI & Advanced Oxide Slurries
- Copper Bulk Slurries
- Copper Barrier Slurries
- W and new metals (Co, Mo) Slurries
- Post CMP (pCMP) Cleans
- Wafer Polishing Slurries

Leading supplier position with our **Portfolio**



Click below to

- check out our <u>EMD solutions</u>
- see our legacy <u>Versum offering</u>

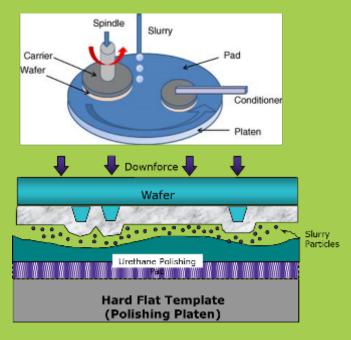


GLOBAL LEADER IN CMP TECHNOLOGY

- Performance tested products with long POR track-record with leading global foundry and memory fabs.
- Products are designed to provide high tunability and wide process windows to meet broad customer performance requirements.
- Highly experienced applications engineers/technology/commercial team to work with customers on the tool for product adoption.

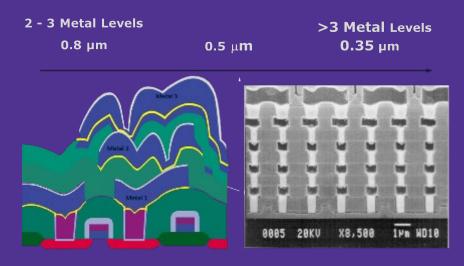


What is CMP?



Chemistry and abrasion is used to polish the wafer surface

Why is CMP needed?



Without CMP

- Large Depth-of-Focus required
- Large Thickness Etch required
- Poor Step Coverage

With CMP

- Uniform and Planar Surface
- Higher Performance
- Improved Die Yields and Device Reliability
- Simplified Lithography



Our Offerings & Application Areas

Integrated CMP and pCMP Offerings

FEOL Dielectrics STI, ILD & Oxides

STI2100/STI 2305/STI 2503 STI2401/STI2910 STI2601/2TI2910

HPD 8XXX (Development)

- Reduced defectivity
- High Selectivity (Nitride and Poly)
- Low oxide dishing

CeClean 2020 CeClean 2022

- Ceria nano particle removal
- Reduced Defect
- Increased PVA brush life

MOL MG & Contacts W and Co

W5X00 Co7000 (Co Bulk) Co7200 (Co Barrier)

- Dishing improvements
- Low defectivity
- Removal rate tuning

WPC1090 (acidic)

CP98D (alkali)

- Corrosion control
- Metal contamination
- Reduce particle defect

BEOL interconnect Cu Bulk /Barrier

Cu3980/Cu3086 (Cu Bulk) Cu4545/BAR6610R (Cu Barrier) BAR6520 (Cu Barrier)

- Low defectivity
- Optimized COO
- Tunable selectivity
- •Compatible w. new metals Co/Ru

CP72B: Cu, CP98D: Cu/Co CP1002: Cu/Co/Ru

- Corrosion control
- Organic residue removal
- •Reduce metals & particle defect

pCMP Cleans

Development Product



Global capabilities & capacities

Tempe, Arizona

Manufacturing
Scale-up Engineering
Research & Development
Application Support

Dallas, Texas

Manufacturing Scale-up Engineering

In all regions

Dedicated sales and customer service

Share Supplier Chain

Materials planning & Logistics

Transportation & Warehousing

Europe

Application Support

China

Application Support

Mie, Japan

Manufacturing
Scale-up Engineering
Application Support

Hsinchu Taiwan

Manufacturing
Scale-up Engineering
Research & Development
Application Support

Singapore

Application Support

Pyeongtaek, Korea

Manufacturing Scale-up Engineering Research & Development Application Support

Manufacturing

- Tainan, Taiwan
- Mie, Japan
- Tempe, AZ USA
- Dallas, TX, USA
- Pyeongtaek, Korea

R&D and Applications

- Tempe, AZ U.S.A.
- Hsinchu, Taiwan
- Pyeongtaek, Korea



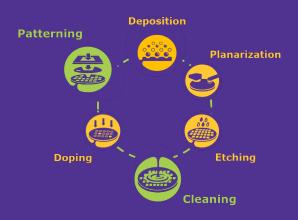
our combined products & capabilities

Patterning





patterning solutions



Enable advanced **patterning solutions** for next generation devices



Products

Photoresists

Anti-reflective & Underlayer Coatings

Process Enhancement Solutions

Cleaning Solutions (SP&C)



R&D

Revolutionary patterning materials (e.g. DSA)

Pattern enhancement materials for Patterning

High performance Photoresist for specialty applications

High purity cleaning Solutions



Key locations





our portfolio

Our vision: Enable advanced patterning solutions for next generation devices



Strong portfolio supporting image transfer steps in semiconductor

- Photoresists
- Anti-reflective & Underlayer Coatings
- Process Enhancement Solutions
- Cleaning Solutions (SP&C)

Click below to

- check out our **EMD** solutions
- see our legacy <u>Versum offering</u>



our focus

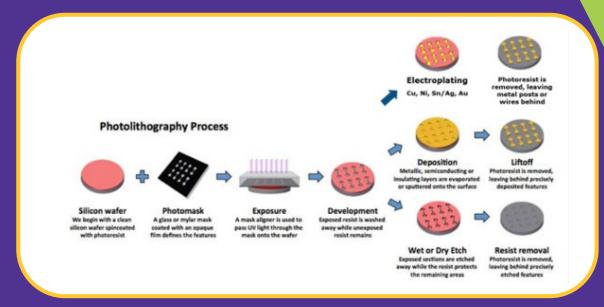
enable the growth through innovation and market position

The Markets:

- Support Moore's Law oriented Leading Edge innovation
- Enable novel material solutions for 'More than More' technologies
- Drive development for Patterning in advanced Wafer Level Packaging

Innovative Solutions:

- Highly innovative Lithography materials
- Advanced Surface Prep and Cleans Solutions



- Growth driven by semiconductor device miniaturization, adoption of 3D structures and introduction of new material stacks
- Leverage TEL and SCREEN OEM relationships to amplify innovation cycles



application areas

- Lithography: i-line & KrF wavelength for
 - 3D NAND staircase patterning
 - **Electroplating** (bumping, RDL, Cu pillars)
 - Metallization by Lift-Off (SAW devices)
 - High AR **implants** (CIS)
 - Litho on special substrates SiC, GaAs, GaN
- Advanced patterning: Directed selfassembly (DSA)
- Litho process enhancement:
 defect control, shrink, anti-reflex coating, pattern collapse
- Multi layer etch stacks: CUL, MHM
- Cleaning: resist & etch residue removal
- Advanced selective etch

our offerings

Patterning Solutions

- Existing: i-line & KrF Photoresists
- New: DSA, Metal HM, lift-off KrF resist

Process Enhancement Solutions

- Existing: TARC (AZ AQUATAR VIII®), Shrink, BARC (AZ BARLI®), Rinse
- New products: Solid Rinse, EUV Rinse

Process Materials

• Existing: Edge Bead Removers, Polyimide Developers, MIF & Inorganic Developers

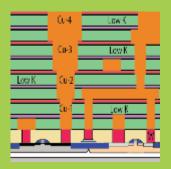
Cleaning Solutions (Front-End, Back-End & Packaging)

- Existing: Post Etch Residue Removers, Resist Removers,
- New Products: Selective Etchants, Solid Clean



Surface preparation and cleans Business at Glance

Advanced IC Cleans



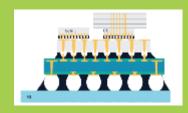
- MHM PERRs: HX-210 series, BHP-800s
- Selective Si/SiGe Etchants: SG series*, AFE series
- Selective SiN: ANR series*

TFRR and Wafer Level Packaging Cleans



SINGLE DIE PACKAGING CLEANS

- **Pre-wired bond cleans:** BPS 100, BPS 106, BPS 170, BPS 600, NE111
- Dicing Cleans: BPS 729A, BPS 729B



ADVANCED PACKAGING CLEANS

- Thick Film Resist Removers:

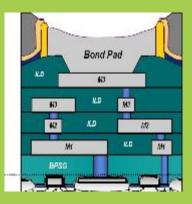
 Dynastrip®

 AP7990T, AP7880T, AP8070

 Dynastrip®AP7900C, Dynastrip®

 AP1050
- PERRs & Si recess etchants: NE89, XT1100, EZSTRIP®528H, VSEs, Dynastrip® DL9150

Legacy PERR IC Cleans



- **HA based:** ACT® 915A, ACT® 927C, ACT® 935, ACT® 940, ACT® 945, ACT® 114A, ACT® FLT101
- F-based: ACT® NE14, NE89, NE111, EZSTRIP®528H
- Solvent-based: ACT® CMIK-S, ACT ®690S/SX
- Semi-aqueous: ACT®970

Polymer Removal



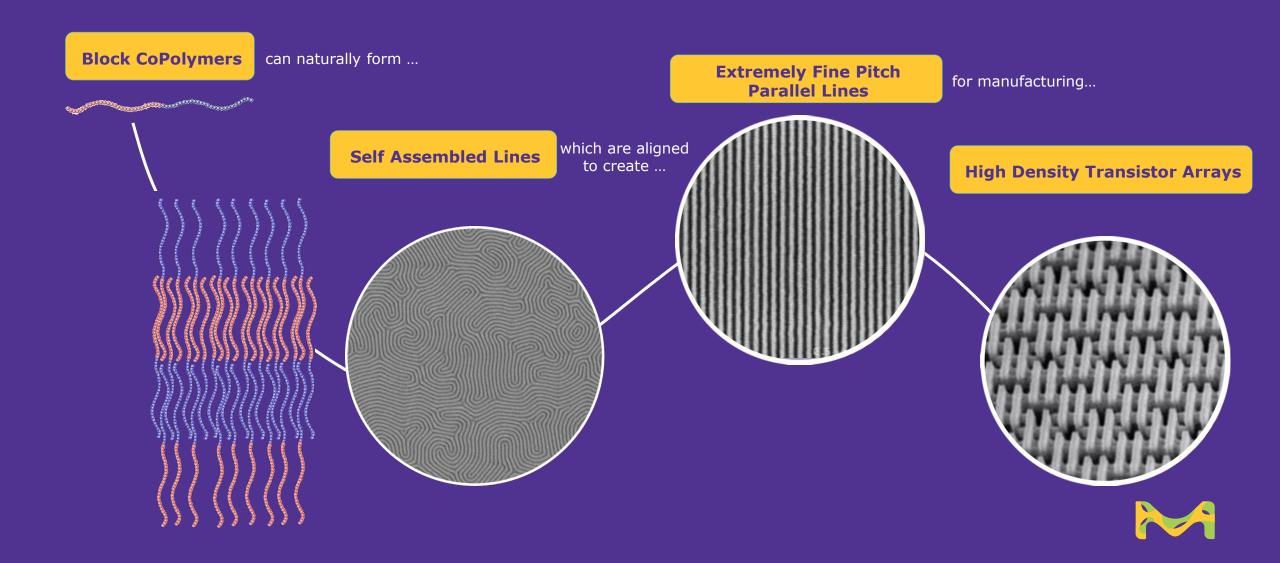
- Anhydride-cured Epoxy/Urethane Remover: Dynasolve® 711
- Amine-cured Epoxy Remover: Dynasolve® AP185
- Silicone Remover: Dynasolve®200s
- Acrylic Remover: Dynasolve® 699



Global capabilities & capacities



Directed self assembly (DSA) Fine patterning from Self-Assembling materials, rather than lithography



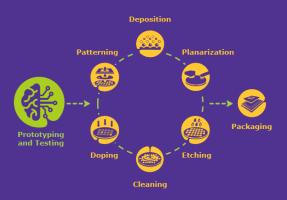
our combined products & capabilities

Intermolecular





intermolecular



INTERMOLECULAR®

We are **THE TRUSTED PARTNER** for Materials Innovation.

We **explore, characterize and develop advanced materials** that are revolutionizing the next generation of electronics that make lives easier, entertaining and more productive.

Key location

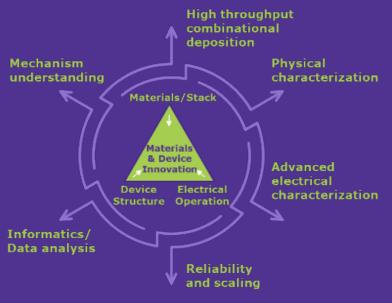




- Semiconductor:

 NVM, DRAM, 3D-NAND,
 Logic
- Display
- Quantum Computing

Enabling Higher ValueDevelopment





inter-olecular

our portfolio



- Accelerate development and screening of innovative materials
- Generate data which correlate materials, process, physical properties, and electrical performance
- Collaborate with customers who utilize the generated data to make confident material decisions

Click **here** to visit our Intermolecular website!



INTERMOLECULAR®

Independent Materials Innovation as a Service



High Through-put Experimentation



- Advanced capability on combinatorial tools
- Correlations established between materials, physical properties and electrical performance

High Quality Material Development Services

- SOW collaboratively defined to meet client's needs
- High quality, repeatable data generated by a highly skilled cross functional team

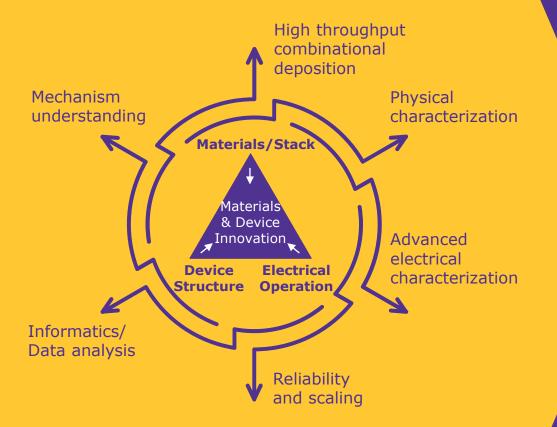
Trusted Partner for Materials Innovation



- Protocols established to maintain confidentiality
- The client owns and can file IP on any deliverables executed by Intermolecular



The Trusted Partner for Materials Innovation



Enabling Higher Value Development





Leading-Edge Team, Capabilities, & Methodologies

- Broad spectrum of expertise in materials, process, equipment, characterization and device integration
- Extension of the customer's team, working together with Intermolecular custom-built tools, workflows and data analysis systems



Accelerate Learning with High Quality, Impactful Data for Decision-Making

- Statistically significant data
- Correlating materials, processes, physical properties, optical properties and electrical performance



Proven Record for Maintaining Confidentiality

- Protocols established to manage confidential information
- Client owns and can file IP on any deliverable produced by Intermolecular



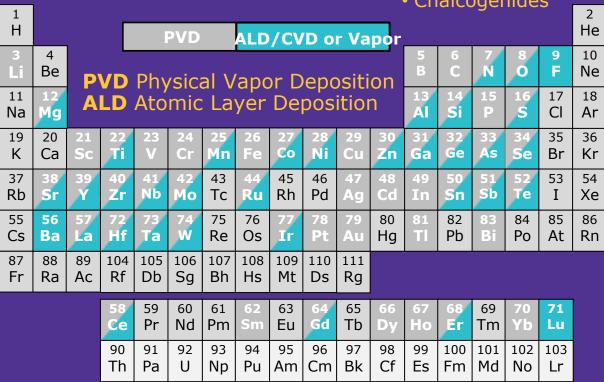


our offerings

- Thin film depositions
- Wet Chemistry
- Physical characterization
- Optical characterization
- Electrical characterization
- Simple test vehicles (or can utilize customer test vehicles)
- Workflows, combining depositions and characterizations, to screen materials and process spaces
- Integration learning
- Mechanism understanding

experience.

- Metal Oxides
- Metal Nitrides
- Metals
- Alloys
- Chalcogenides





INTERMOLECULAR®

who we are

We are **THE TRUSTED PARTNER** for materials innovation.

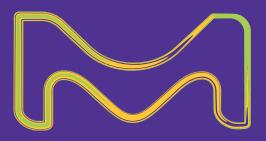
We **explore, test and develop advanced materials** that are revolutionizing the next generation of electronics that make lives easier, entertaining and more productive. For more than 15 years, our team, methodologies and quality data have driven impactful outcomes, market opportunities and innovative product designs for our customers.

As the Silicon Valley science hub of the Performance Materials business of Merck KGaA, Darmstadt, Germany, we are perfectly positioned to break the boundaries of science and technology. We advance digital living!



products & capabilities

Delivery Systems and Services





pelivery systems & services

Trusted Global leader in the Safe and reliable delivery of hazardous materials to the semiconductor industry





OEM/IDM-aligned New Product Development

Key locations





Slurry Delivery

Fab Services

Precursor Delivery

Spec Gas Delivery FLOWMASTER® CMP

MEGASYS®

CHEMGUARD® CHEMKEEPER®

GASGUARD®

GasSTAR®
GASKEEPER®

NPD DRIVERS

Higher capacity supply modes
Materials compatibility
Materials properties
Cost of ownership
Controls systems
Safety



psæs portfolio

Deposition Patterning Specialty Materials

Delivery

Systems

Doping



Etching

Leading positions in...

- ... specialty chemical delivery CHEMGUARD® | CHEMKEEPER®
- specialty gas delivery
 GASGUARD® | GASKEEPER®
- ... CMP slurry delivery
 FLOWMASTER® CMP & POLYFLOW™ Parts/Carrier Cleaners
- ... onsite in-fab services
 MEGASYS®

Click **here** to see our DSS offering online!



Trusted Global leader in the safe and reliable delivery of hazardous materials to the semiconductor industry





FAB NEEDS and DS&S offerings

FAB PROJECTS for BULK SPECIALTY GASES





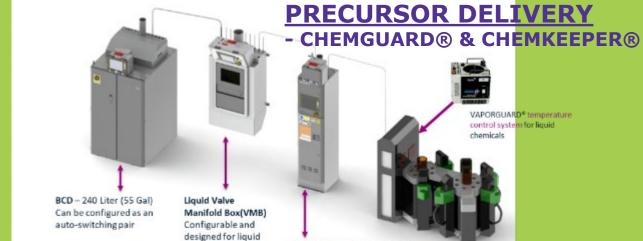
UHP service

SLURRY DELIVERY - FLOWMASTER® CMP



FAB SERVICES

- MEGASYS®



CHEMGUARD® Delivery Systems interface to most semiconductor

manufacturing tools and has been hazop'd approved to deliver over 200 different molecules used HVM

SPEC GAS DELIVERY- GASGUARD® | GasStar® | Gaskeeper®

Post in

new product pevelopment

DRIVERS

R&D capabilities and **New Product Development**

The Semiconductor industry is experiencing the "Age of Materials" and EMD is positioned to capitalize – but the Age of Materials can not happen without the Equipment to enable it

- Higher capacity supply modes
- Materials compatibility
- Materials properties (solids, lvp liquids)
- Cost of ownership (footprint, uptime)
- Controls systems
- Safety



psæs production locations & capabilities



Pennsylvania

Vultee Street, **Allentown**

North America Manufacturing - Gas & Chem Equipment

Sales, Administration, Product Management, Procurement

TEKPark, Breinigsville

North America Engineering & Product Development

Tempe, Arizona

Business Headquarter North America



Korea Business Headquarter

Hsinchu, Taiwan

Toll Manufacturing



VMHYT

Korea Manufacturing -Gas & Chem Equipment

Sales, Administration, Product Management, Procurement, Engineering



Headquarter

China/Taiwan Business

Wai Gao Qiao

Shanghai,

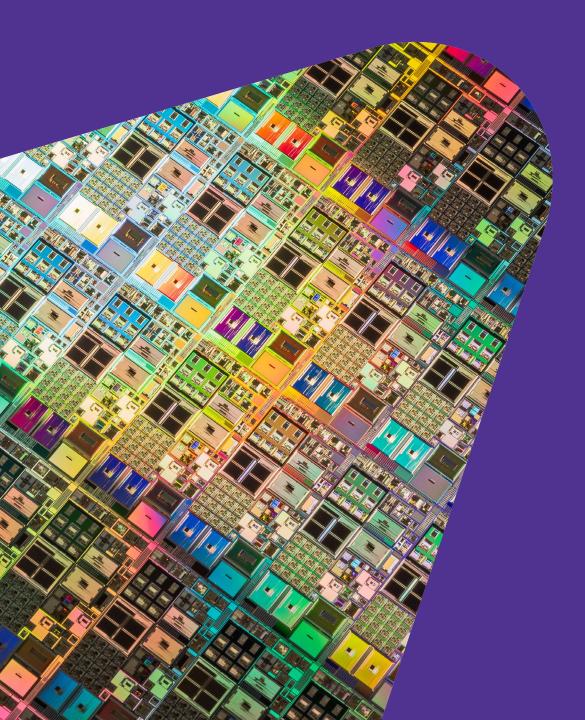
(WGQ)

China

China Manufacturing -Gas & Chem Equipment

Sales, Administration, Product Management, Procurement





Locations overview



our truly Global Footprint

will enable unparalleled customer partnership

San Jose, CA HQ Intermolecular

Tempe, AZ HO Versum

United States

- 9 production sites
- 8 technical centers

Europe

- 3 production sites
- 3 technical centers

China

- 2 production sites
- 1 technical centers

South Korea

- 7 production sites
- 4 technical centers

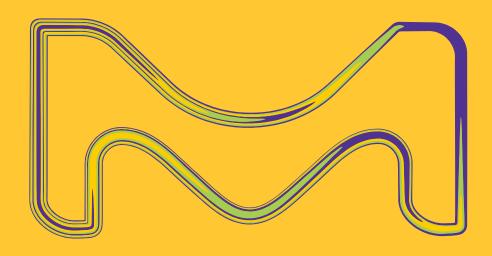
Taiwan

- 4 production sites
- 3 technical centers

Japan

- 1 production sites
- 1 technical centers

Darmstadt, DE



EMD Performance Materials, the vibrant M, Super-Q, AZ, Spinfil, AP-LTO, AP-LTN, AQUATAR, BARLI, ACT, EZSTRIP, Dynastrip, Dynasolve, Intermolecular, FLOWMASTER, POLYFLOW, MEGASYS, CHEMGUARD, CHEMKEEPER, GASGUARD, GasSTAR and GASKEEPER are trademarks of Merck KGaA, Darmstadt, Germany or its affiliates. All other trademarks are the property of their respective owners. Detailed information on trademarks is available via publicly accessible resources.

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